AMENDMENT UNDER 37 C.F.R. 1.116 – EXPEDITED PROCEDURE

Serial Number: 10/758,055 Filing Date: January 15, 2004

Title: METHOD FOR REDUCING SOCKET WARPAGE

Assignee: Intel Corporation

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IN THE ABSTRACT OF THE DISCLOSURE

Please amend the Abstract as follows:

A method and a structure for reducing socket warpage <u>in an embodiment by forming at</u>

<u>least one groove in a socket housing contiguous to a surface mount region for an electrical device</u>

and securing a rigid bar in the groove.